



### General Specifications

|                    |                             |
|--------------------|-----------------------------|
| Resistive Element: | Thick film                  |
| Substrate:         | Aluminum nitride ceramic    |
| Terminals:         | Tin/Lead, 90/10 over nickel |

### Electrical Specifications

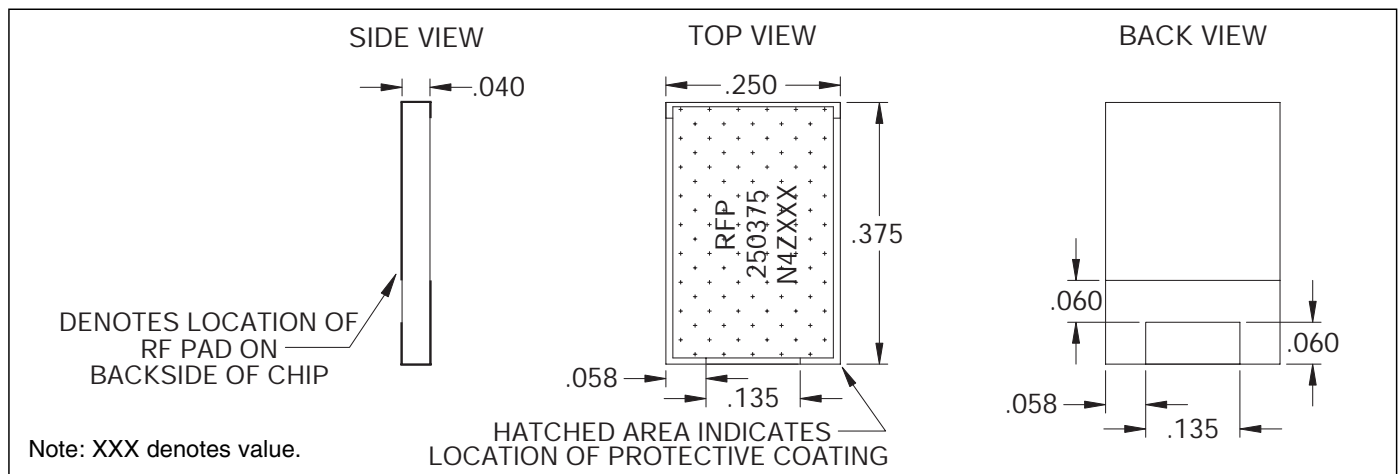
|                   |              |
|-------------------|--------------|
| Resistance Value: | 50 ohms, ±2% |
| Frequency Range:  | DC - 3.0 GHz |
| Power:            | 25 Watts     |
| V.S.W.R.:         | 1.25:1       |

**Notes:** Tolerance is ±.010, unless otherwise specified. Operating temperature is -55°C to +125°C (see chart). Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions are in inches.  
**Specifications subject to change without notice.**

### Features

- DC – 3.0 GHz
- 25 Watts
- Aluminum Nitride (AlN) Ceramic
- Surface Mountable
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

### Outline Drawing



Available on Tape and Reel for Pick and Place Manufacturing.

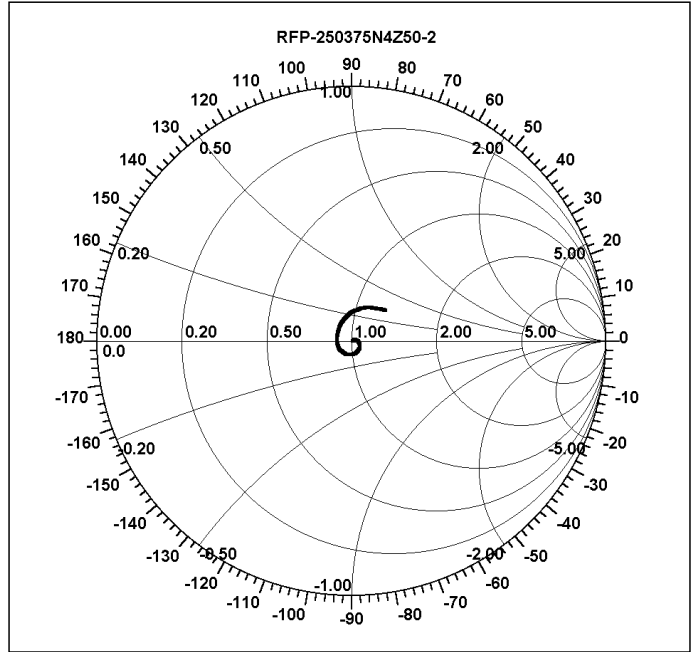
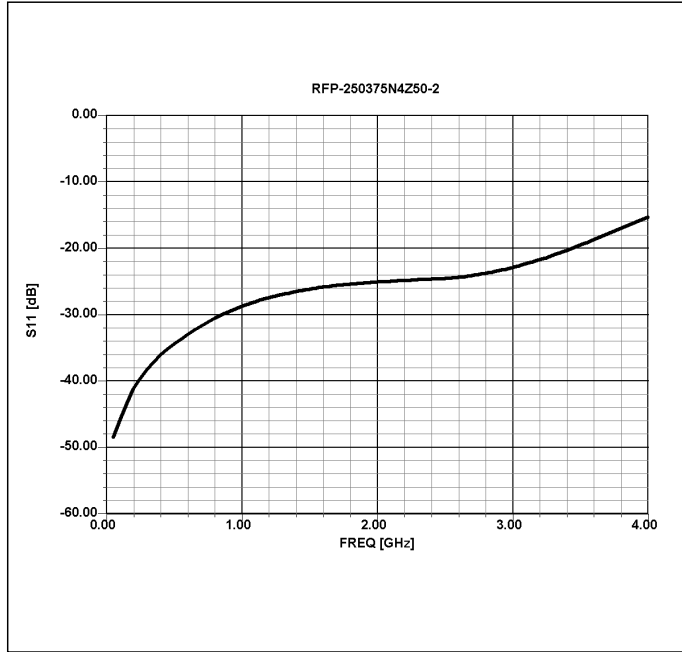
Sales Desk USA: Voice: (800) 544-2414 Fax: (315) 432-9121  
Sales Desk Europe: Voice: (+44) 23 92 232392 Fax: (+44) 23 92 251369

# Model RFP-250375N4Z50-2

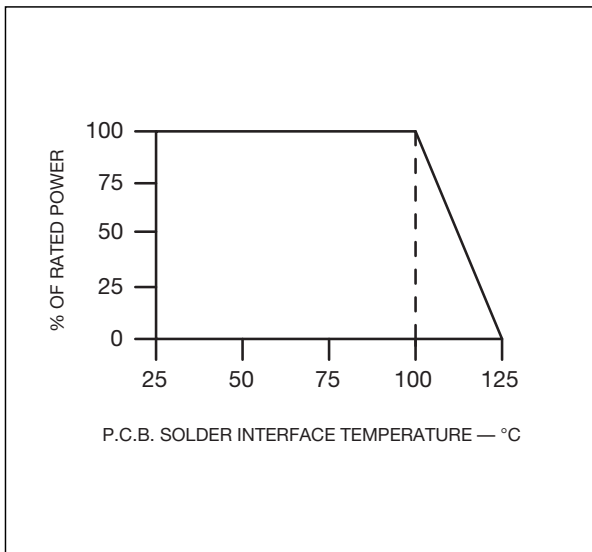


**RF Power**

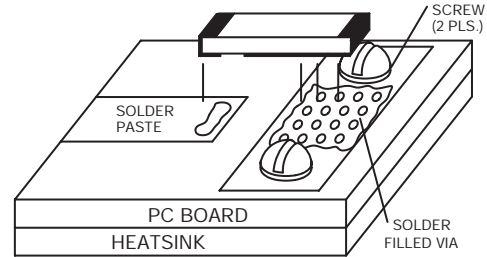
## Typical Performance



## Power Derating



## Suggested Mounting Procedures



1. Solder part in place using 60/40 type solder with controlled temperature iron (700°F).
2. Drill thermal via through PCB and fill with solder, such as 60/40 type.
3. To ensure good thermal connectivity to heat sink, drill and tap heatsink and mount PCB board to heat sink using screws.

Available on Tape and Reel for Pick and Place Manufacturing.

